REV LETTER: E PAGE NO: 1 OF 1 PART NUMBER:

Polymer PTC Devices

Surface mount fuses

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LP-SM130

Features

- □ Small size of 1812
- □ Fast tripping resettable circuit protection
- □ Surface mount packaging for automated assembly
- Agency Recognition: UL、CSA、TUV Mus International Agency Recognition: UL Age

Product Dimensions (mm)

	Α	В	С	D
Part number —	Max	Max	Max	Max
LP-SM130	9.50	3.00	6.71	0.70
t _B	C .	Part Ma	rking System	

Side View

End View



Electrical Characteristics

Dort number	I _H	Ι _Τ	V _{max}	I _{max}	T _{trip}	0	Pd _{typ}	R _{min}	R_{1max}
Part number	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	()	()
LP-SM130	1.30	2.60	33	40	8.0	4.0	2.1	0.080	0.280

 I_{H} =Hold current: maximum current at which the device will not trip at 25 still air.

 I_T =Trip current: minimum current at which the device will always trip at 25 still air.

V_{max}=Maximum voltage device can withstand without damage at rated current.

 $I_{\text{max}} = Maximum$ fault current device can withstand without damage at rated voltage.

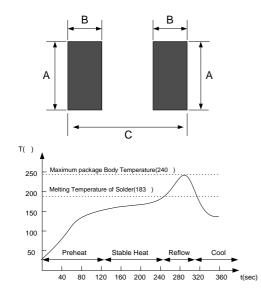
 T_{trip} =Maximum time to trip(s) at assigned current.

Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min}=Minimum device resistance at 25 prior to tripping.

R1max=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number –	Α	В	С
Fait number	(mm)	(mm)	(mm)
LP-SM130	4.6	2.3	10.7

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 2000pcs per reel.

